

ABSTRACT

One disclosed embodiment comprises a substrate having a top surface for receiving two or more semiconductor dies. The disclosed embodiment further comprises a printed circuit board attached to a bottom surface of the substrate and at least one via in the substrate. The at least one via provides an electrical connection between a signal bond pad of a first semiconductor die and the printed circuit board. The at least one via provides an electrical connection between a first substrate bond pad and the printed circuit board. The first substrate bond pad is connected to the first signal bond pad of the first semiconductor die by a first signal bonding wire. The at least one via also provides an electrical connection between the first signal bond pad of the first semiconductor die and a first land that is electrically connected to the printed circuit board.

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